

<Intelligent Power Modules>

PM100RG1B120

FLAT-BASE TYPE INSULATED PACKAGE



FEATURE

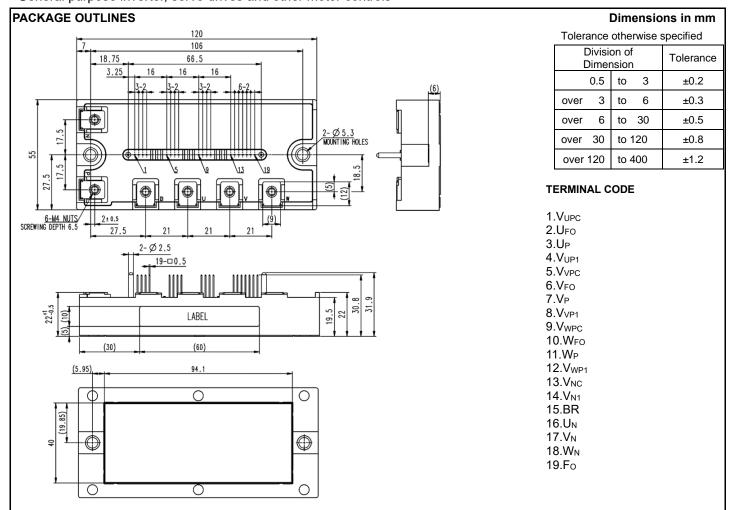
- a) Adopting Full-Gate CSTBT™ chip.
- b) The over-temperature protection which detects the chip surface temperature of CSTBTTM is adopted.
- c) Error output signal is available from each protection upper and lower arm of IPM.
- d) Outputting an error signal corresponding to the abnormal state (error mode identification)

UL Recognized under UL1557, File No. E323585
This product is compliant with the Restriction of the Use of Certain Hazardous Substances in Electrical and Electronic Equipment (RoHS) directive 2011/65/EU and (EU)2015/863.

APPLICATION

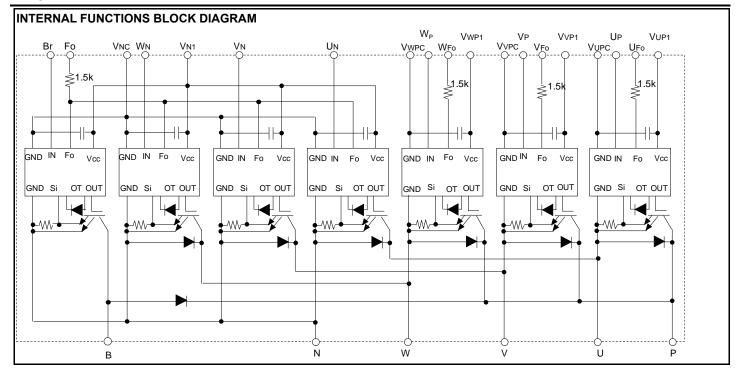
Publication date: December, 2020

General purpose inverter, servo drives and other motor controls



HIGH POWER SWITCHING USE

INSULATED TYPE



MAXIMUM RATINGS (Tvj = 25°C, unless otherwise noted)

INVERTER PART

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Symbol	Parameter	Conditions	Ratings	Unit			
V _{CES}	Collector-Emitter Voltage	V _D =15 V, V _{CIN} =15 V	1200	V			
Ic	Collector Current	T _C =25 °C	100	_			
I _{CRM}	Collector Current	Pulse	200	Α			
P _{tot}	Total Power Dissipation	T _C =25 °C	595	W			
l _E	Emitter Current	T _C =25 °C	100	_			
I _{ERM}	(Free-wheeling Diode Forward current)	Pulse	200	Α			
Tvj	Junction Temperature	(Note5)	-20 ~ +150	°C			

^{*:} Tc measurement point is just under the chip.

BRAKE PART

Symbol	Parameter	Conditions	Ratings	Unit
V_{CES}	Collector-Emitter Voltage	V _D =15 V, V _{CIN} =15 V	1200	V
I _C	O. H. et al. O. annut	T _C =25 °C	50	
I _{CRM}	Collector Current	Pulse	100	Α
P _{tot}	Total Power Dissipation	T _C =25 °C	378	W
V _{R(DC)}	Diode Rated Reverse DC Voltage	T _C =25 °C	1200	V
I _F	Diode Forward Current	T _C =25 °C	50	Α
Tvj	Junction Temperature	(Note5)	-20 ~ +150	°C

^{*:} To measurement point is just under the chip.

CONTROL PART

Symbol	Parameter	Conditions	Ratings	Unit
V_D	Supply Voltage	Applied between: V _{UP1} -V _{UPC} , V _{VP1} -V _{VPC} , V _{WP1} -V _{WPC} , V _{N1} -V _{NC}	20	V
V_{CIN}	Input Voltage	Applied between: U_P - V_{UPC} , V_P - V_{VPC} , W_P - V_{WPC} , U_N , V_N , W_N , W_N , W_N	20	V
V_{FO}	Fault Output Supply Voltage	Applied between: U _{FO} -V _{UPC} , V _{FO} -V _{VPC} , W _{FO} -V _{WPC} , Fo-V _{NC}	20	V
I _{FO}	Fault Output Current	Sink current at U _{FO} , V _{FO} , W _{FO} , Fo terminals	20	mA

HIGH POWER SWITCHING USE

INSULATED TYPE

TOTAL SYSTEM								
Symbol	Parameter	Parameter Conditions		Unit				
V _{CC(PROT)}	Supply Voltage Protected by SC	V _D =13.5 V~16.5 V, Inverter Part, Tvj=+125°C start	800	V				
T _{stg}	Storage Temperature	-	-40 ~ +125	°C				
Tc	Operating Case Temperature	(Note5)	-20 ~ +125	°C				
V _{isol}	Isolation Voltage	60Hz, Sinusoidal, Charged part to Base plate, AC 1min, RMS	2500	V				

^{*:} Tc measurement point is just under the chip.

THERMAL RESISTANCE

Symbol	Parameter	Conditions	Limits			Unit
		Conditions	Min.	Тур.	Max.	Unit
$R_{th(j-c)Q}$		Inverter, Junction to case, IGBT, per 1 element (Note1)	-	-	0.21	
$R_{th(j-c)D}$	Thermal Resistance	Inverter, Junction to case, FWD, per 1 element (Note1)	,		0.31	K/W
$R_{th(j-c)Q}$	Thermal Resistance	Brake, Junction to case, IGBT, per 1 element (Note1)			0.33	
$R_{th(j-c)D}$		Brake, Junction to case, FWD, per 1 element (Note1)			0.51	
R _{th(c-s)}	Contact Thermal Resistance	Case to heat sink, per 1 module, Thermal grease applied (Note.1, 2, 5)	-	14.4	-	K/kW

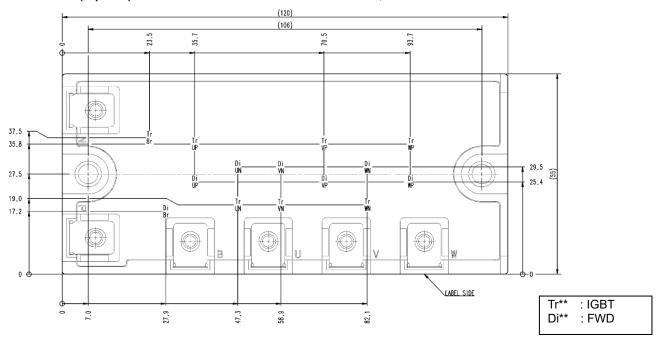
Note1. If you use this value, $R_{\text{th(s-a)}}$ should be measured just under the chips.

Note2. Typical value is by thermally conductive grease of λ =0.9W/(m·K), D_(C-S)=50 μ m.

CHIP LOCATION (Top view)

Publication date: December, 2020

Dimension in mm, torelance: ±1mm



<Intelligent Power Modules>

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HIGH POWER SWITCHING USE

INSULATED TYPE

ELECTRICAL CHARACTERISTICS (Tvj= 25°C, unless otherwise noted)

INVERTER PART

Complete		Conditions			Limits			1.124
Symbol	Parameter	Condition	Conditions			Тур.	Max.	Unit
		V _D =15 V, I _C =100 A	Tvj=25 °C	Terminal	-	-	1.85	
V	Collector-Emitter Saturation Voltage		1 Vj-25 C	Chip	-	1.3	-	V
V _{CEsat}	Conector-Emitter Saturation voltage	V _{CIN} =0 V, Pulsed, (Fig.1)	Tvj=125 °C	Terminal	-	-	2.1	V
		V _{CIN} -0 V, Pulsed, (Fig. 1)	1 Vj - 125 C	Chip	1	1.5	-	
		V _D =15 V, I _E =100 A, Tvj=25 °C	Tvi=25 °C	Terminal	-	-	2.4	
\/	Emitter-Collector Voltage		1 Vj-25 C	Chip	1	1.75	-	V
V _{EC}		V _{CIN} = 15 V, pulsed, (Fig.2) Tvj=125 °C	Tvi=125 °C	Terminal	1	-	2.65	
			Chip	1	1.95	-		
ton		V _D =15 V, V _{CIN} =0 V↔15 V,		0.3	0.8	1.2		
t _{rr}		V _{CC} =600 V, I _C =100A,		-	0.2	0.4		
t _{c(on)}	Switching Time	Tvj=125 °C,			-	0.2	0.4	μs
t _{off}		Inductive Load			- 1.	1.1	2.8	
t _{c(off)}		(Fig.3, 4)			-	0.4	1.2	
	Collector-Emitter Cut-off Current	V _{CE} =V _{CES} , V _D =15 V, V _{CIN} =15 V (Fig.5)		Tvj=25 °C	-	-	1	Л
I _{CES}				Tvj=125 °C	-	-	10	mA

BRAKE PART

Symbol	Parameter	Conditions			Limits			Unit
Syllibol	Farameter				Min.	Тур.	Max.	Offic
		V _D =15 V, I _C =100A	Tvj=25 °C	Terminal	-	-	1.75	
	Collector Emitter Seturation Voltage	VD-13 V, 16-100A		Chip	-	1.3	-	V
V_{CEsat}	Collector-Emitter Saturation Voltage	V _{CIN} =0 V, Pulsed, (Fig.1)	Tvj=125 °C	Terminal	-	-	2.0]
		V _{CIN} -0 V, Fuised, (Fig. I)	I Vj = 125 C	Chip	-	1.5	-	
			Tvj=25 °C	Terminal	-	-	2.35	V
\/	Diode Forward Voltage			Chip	-	1.75	-	
V_{FM}	Diode Forward Voltage	I _F =100A	Tvj=125 °C	Terminal	-	-	2.6	
				Chip	-	1.95	-	
	Collector-Emitter Cut-off Current	\\ -\\ \\ -15\\\\ -15\\\\	<i>E</i>)	Tvj=25 °C	-	-	1	A
I _{CES}	Collector-Emitter Cut-off Current	$V_{CE}=V_{CES}$, $V_{D}=15$ V, $V_{CIN}=15$ V (Fig.5)		Tvj=125 °C	-	-	10	mA

HIGH POWER SWITCHING USE

INSULATED TYPE

ELECTRICAL CHARACTERISTICS (Tvj = 25°C, unless otherwise noted)

CONTROL PART

Cumhal	Parameter	Conditions	Conditions		Limits		
Symbol	Parameter	Conditions			Тур.	Max.	Unit
		V -15 V V -15 V	V _{P1} -V _{PC}	-	4	6	
	Circuit Current	V _D =15 V, V _{CIN} =15 V	V _{N1} -V _{NC}	-	16	24	^
I _D	Circuit Current	V_D =15 V, V_{CIN} =0 V \longleftrightarrow 15 V, V_{CC} =800 V	V _{P1} -V _{PC}	-	29	35	mA
		I _C =0A, Tvj=125 °C, f _C ≤20kHz	V _{N1} -V _{NC}	-	103	120	
$V_{th(ON)}$	Input ON Threshold Voltage	Applied between:		1.2	1.5	1.8	V
$V_{th(OFF)}$	Input OFF Threshold Voltage	$U_{P}\text{-}V_{UPC},\ V_{P}\text{-}V_{VPC},\ W_{P}\text{-}V_{WPC},\ U_{N},\ V_{N},\ W_{N},$	Br-V _{NC}	1.7	2.0	2.3	V
00	Short Circuit Trip Level	00 IT 1 4405 00 W 45 W (F) 0 0	Inverter	200	-	-	Α
SC		-20≤Tvj≤125 °C, V _D =15 V (Fig.3, 6)	Brake	100	-	-	
t _{d(SC)}	Short Circuit Current Delay Time	V _D =15 V, Tvj=125 °C (Fig.3, 6)	V _D =15 V, Tvj=125 °C (Fig.3, 6)		2.0	-	μs
ОТ	0 7 1 0 1 1	Detect to see a set up of ICRT chin confee	Trip level	150	-	-	°C
OT _(hys)	Over Temperature Protection	Detect temperature of IGBT chip surface	Hysteresis	-	20	-	°C
UV _t	Supply Circuit		Trip level	11.0	12.0	12.7	.,
UV _r	Under-Voltage Protection	-	Reset level	-	12.5	-	V
I _{FO(H)}	Facility Control of Community	V 45 V V 45 V (N-4-0)		-	-	0.01	4
I _{FO(L)}	Fault Output Current	V _D =15 V, V _{FO} =15 V (Note3)		-	10	15	mA
			ОТ	-	8.0	-	
t _{FO}	Fault Output Pulse Width	V _D =15 V (Note3)	UV	-	4.0	-	ms
			sc	-	2.0	-	

Note3. Fault output is given only when the internal SC, OT & UV protections schemes of either upper or lower arm device operate to protect it.

MECHANICAL RATINGS AND CHARACTERISTICS

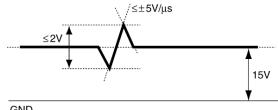
Cumbal	Parameter	Conditions		Limits		
Symbol		Conditions	Min.	Тур.	Max.	Unit
Ms	Mounting Torque	Mounting part screw : M	5 2.5	3.0	3.5	N•m
M_t	Mounting Torque	Main terminal part screw : M	1.5	1.7	2.0	INTIII
m	mass	-	-	260	-	g

RECOMMENDED CONDITIONS FOR USE

Publication date: December, 2020

Symbol	Parameter	Conditions	Recommended value	Unit
V _{CC}	Supply Voltage	Applied across P-N terminals	≤ 800	V
V _D	Control Supply Voltage	Applied between : $V_{\text{UP1}}\text{-}V_{\text{UPC}}, V_{\text{VP1}}\text{-}V_{\text{VPC}}, V_{\text{WP1}}\text{-}V_{\text{WPC}}, V_{\text{N1}}\text{-}V_{\text{NC}} \text{(Note4)}$	15.0±1.5	V
V _{CIN(ON)}	Input ON Voltage	Applied between :	≤ 0.8	
$V_{CIN(OFF)}$	Input OFF Voltage	$U_{P}\text{-}V_{UPC},V_{P}\text{-}V_{VPC},W_{P}\text{-}V_{WPC},U_{N},V_{N},W_{N},Br\text{-}V_{NC}$	≥ 9.0] v
f _{PWM}	PWM Input Frequency	Using Application Circuit of Fig. 8	≤ 20	kHz
t _{dead}	Arm Shoot-through Blocking Time	For IPM's each input signals (Fig.7)	≥ 2.5	μs

Note4. With ripple satisfying the following conditions: dv/dt swing $\leq \pm 5$ $V/\mu s$, Variation ≤ 2 V peak to peak



Note5. Long term performance related to thermal conductive material such as thermal grease (including but not limited to aspects such as the increase of thermal resistance due to pumping out, etc.) should be verified under your specific application conditions. Each temperature condition (Tvj, Tc) must be maintained below the maximum rated temperature throughout consideration of the temperature rise even for long term usage.

HIGH POWER SWITCHING USE

INSULATED TYPE

PRECAUTIONS FOR TESTING

- 1. Before applying any control supply voltage (V_D), the input terminals should be pulled up by resistors, etc. to their corresponding supply voltage and each input signal should be kept off state.
 - After this, the specified ON and OFF level setting for each input signal should be done.
- 2. When performing "SC" tests, the turn-off surge voltage spike at the corresponding protection operation should not be allowed to rise above V_{CES} rating of the device.

(These test should not be done by using a curve tracer or its equivalent.)

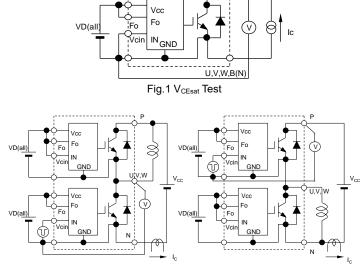
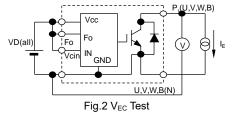


Fig.3 Switching time and SC test circuit



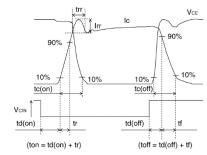


Fig.4 Switching time test waveform

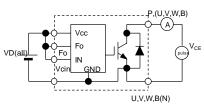


Fig.5 I_{CES} Test

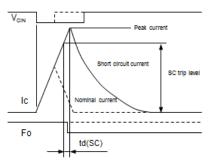
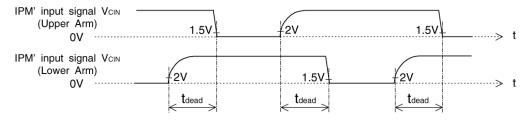


Fig.6 SC test waveform

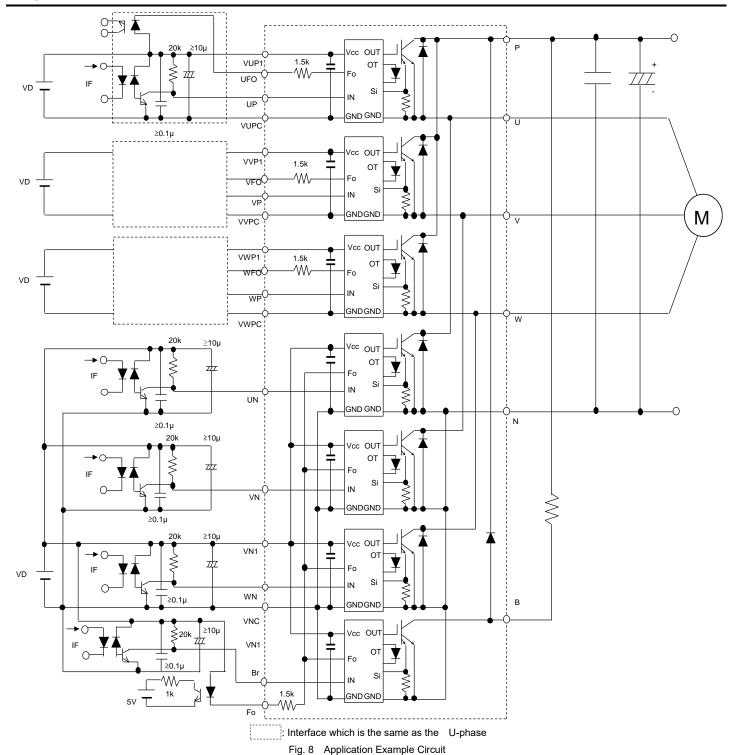


1.5V: Input on threshold voltage Vth(on) typical value, 2V: Input off threshold voltage Vth(off) typical value

Fig. 7 Dead time measurement point example

HIGH POWER SWITCHING USE

INSULATED TYPE

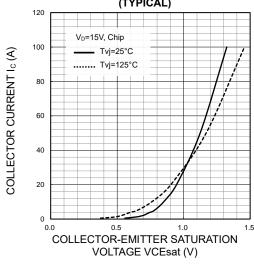


NOTES FOR STABLE AND SAFE OPERATION;

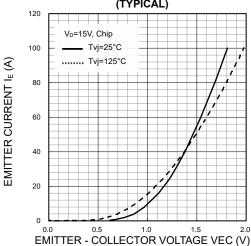
- Design the PCB pattern to minimize wiring length between opto-coupler and IPM's input terminal, and also to minimize the stray capacity between the input and output wirings of opto-coupler.
- · Connect low impedance capacitor between the Vcc and GND terminal of each fast switching opto-coupler.
- Fast switching opto-couplers: t_{PLH}, t_{PHL} ≤ 0.8µs, Use High CMR type.
- Slow switching opto-coupler: CTR > 100% (*can be applied to Brake part input signal, in this case, resistor should be selected properly).
- Use 4 isolated control power supplies (V_D). Also, care should be taken to minimize the instantaneous voltage charge of the power supply.
- Make inductance of DC bus line as small as possible, and minimize surge voltage using snubber capacitor between P and N terminal.

PERFORMANCE CURVES Inverter part

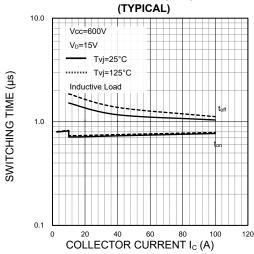




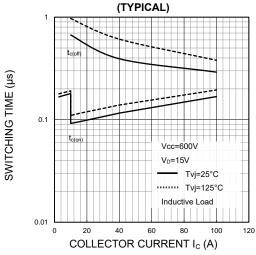
FREE WHEELING DIODE FORWARD CHARACTERISTICS (TYPICAL)



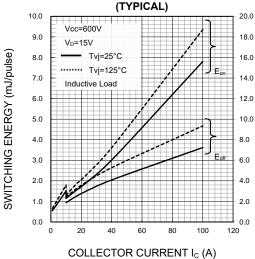
SWITCHING TIME (ton, toff) CHARACTERISTICS (TYPICAL)



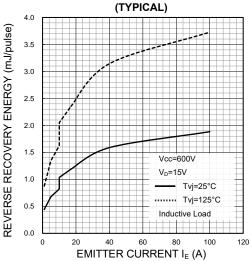
SWITCHING TIME (t_{c(on)}, t_{c(off)}) CHARACTERISTICS

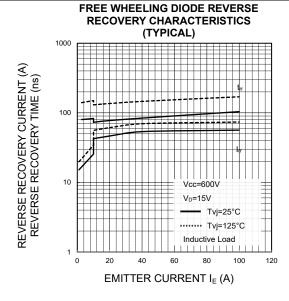


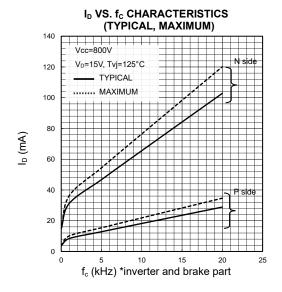
SWITCHING ENERGY CHARACTERISTICS (TYPICAL)

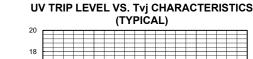


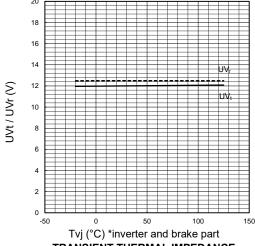
FREE WHEELING DIODE REVERSE RECOVERY ENERGY CHARACTERISTICS

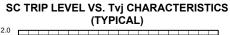


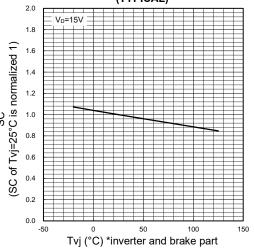












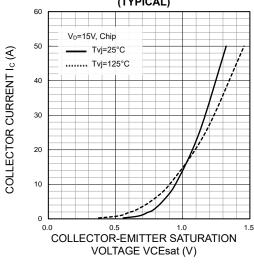
TRANSIENT THERMAL IMPEDANCE **CHARACTERISTICS** (TYPICAL)

	_			
Ri	0.0124	0.0739	0.3505	0.5632
ті (sec)	1.961E-05	0.0014	0.0179	0.0944
10				
1				
		$-\mu$		
0.1				
	/			
0.01				
			+b/: -\O-0 0	11/ 00/
			ing-c)Q=0.2	IN /VV
			th(j-c)D=0.3	1K /W
0.001				
0.00001			0.1	1 10
	-	TIME (s)		
	10 10 10 10 10 10 10 10 10 10 10 10 10 1	10 1.961E-05 10 1.961E-05 10 1.961E-05 10 1.961E-05 10 1.961E-05	10 1.961E-05 0.0014 10 1	10 1.961E-05 0.0014 0.0179 10 1

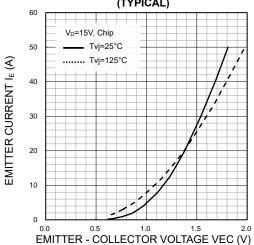
INSULATED TYPE

PERFORMANCE CURVES Brake part

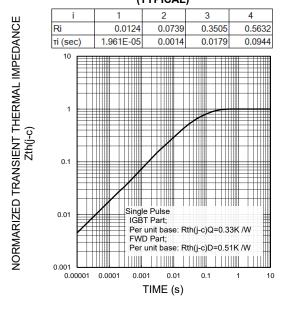
COLLECTOR-EMITTER SATURATION VOLTAGE (VS. Ic) CHARACTERISTICS (TYPICAL)



FREE WHEELING DIODE FORWARD CHARACTERISTICS (TYPICAL)



TRANSIENT THERMAL IMPEDANCE CHARACTERISTICS (TYPICAL)



Note:

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The characteristics curves are presented for reference only and not guaranteed by production test, unless otherwise noted.

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PM100RG1B120

HIGH POWER SWITCHING USE INSULATED TYPE

Important Notice

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HIGH POWER SWITCHING USE INSULATED TYPE

Keep safety first in your circuit designs!

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